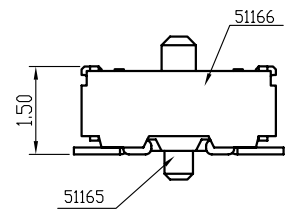
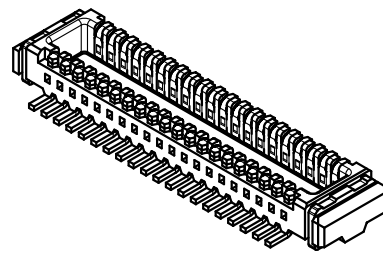


- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - FINISH:
 - CONTACT:
 - 50 μ MIN. NICKEL UNDERPLATING OVERALL.
 - 1:GOLD FLASH PLATING
 - C:15 μ MIN. GOLD ON CONTACT AREA
 - SOLDER:
 - 50 μ MIN. NICKEL UNDERPLATING OVERALL.
 - 1:GOLD FLASH PLATING
 - C:GOLD FLASH PLATING
 - FITTING NAIL:
 - 50 μ MIN. NICKEL UNDERPLATING OVERALL.
 - 80 μ MIN. MATT TIN UNDERPLATING OVERALL.
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-50185-xxxxx
 - PACKAGE PLS. REFER TO PART NUMBER
 - MATING CONNECTOR P/N:51166
 - PART NUMBER
51165-XXX X X- XXX

NO OF CKT	XXX	Polarization	Package
	001	with boss	51165-xxxx-xx-TRP

PACKING: 0.Tape & Reel; 4.Tape & Reel With Mylar

CONTACT PLATING: 1:G/F OVERALL(LEAD FREE); C:15 μ GOLD ON CONTACT AREA



CKT	DIM A	DIM B	DIM C	DIM D	DIM E	DIM F
60	14.06	11.6	13.2	12.5	11.2	12.8
80	18.06	15.6	17.2	16.5	15.2	16.8

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ	DRAWN BY Zhu, Wei	DATE 18/03/20	ACES ELECTRONICS
	CHECKED BY Xu, Zhi Yong	DATE 18/03/20	
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY Xu, Zhi Yong	DATE 18/03/20	TITLE 0.4mm BTB CONN.
	UNITS mm	SIZE A4	DWG NO. 51165-XXXXX-XXX
SCALE 8:1	SHEET NO. 1 OF 1	REV A	PART NO. SEE NOTES